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PATENT APPLICATION

In re application of:

Jun Young Yang

Application No.

09/687,493

Filed:

October 13, 2000

For:

SEMICONDUCTOR PACKAGE HAVING IMPROVED
ADHESIVENESS AND GROUND BONDING

Group No.

2811

Examiner:

(Not Yet Known)



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Assistant Commissioner for Patents
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RESPONSE TO NOTICE TO FILE MISSING PARTS
OF NONPROVISIONAL APPLICATION FILED UNDER 37 CFR §1.53(b)
FILING DATE GRANTED

This is a response to the Notice of Missing Parts of Application - Filing Date Granted mailed on November 27, 2000.